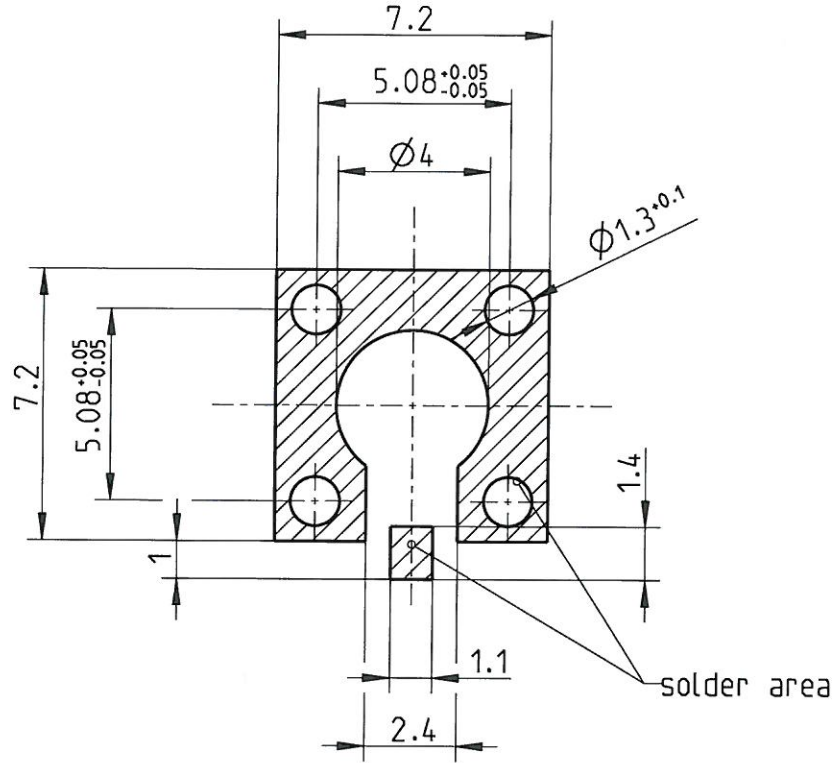


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Leiterplatten-Layout
PCB layout
B 120 c



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A wide variety of transmissionline topologies and pcb-parameters like permittivity, substrate thickness, and board-stackup are applied by customers. These parameters have a strong impact on the high frequency performance of the mounted connector.

Please note, that the given layout is not optimised to fit all of the possible board configurations regarding RF-performance, it represents a recommendation for optimum solderability of the connector.

In order to guarantee optimum high frequency properties of the connector, an RF-analysis of the connector to board transition is recommended.

Formblatt: TCC_Fa_05_Pf_AK_Einsteileit
Prüf: I:Pre-config/Vermerk
Datei: A:\EINZEL\T1_EDB.FRH
Version: 1.2

Dimensions
in mm

ISO-Projektion
Methode E

Rosenberger Hochfrequenztechnik 84526 Tittmoning Pro/ENGINEER				general tolerance ISO 2768 m-H				RN 006-01 dimensions <0,5 and symmetry				scale: 5:1		weight(g): surfacelmm ² :	
				date drawn 11.01.2010 T_Stadler				name check. 13.05.10 [Signature]				title: Leiterplatten-Layout PCB layout			
				date appr. 20.05.10 [Signature]				name dimensioning incl. finish							
a00 10-s325 J_Peterander 19.05.2010				200 10-v084 T_Stadler 16.02.2010				drawing-no.: MB_120C							
100 10-m016 T_Stadler 11.01.2010				distribution to: FE AZ QSM RMT .				X				of: 1			
rev.change-no name date				distribution to:				FE AZ QSM RMT .				X		remarks: .	